Rogers_CombinedEmails_AuthorListConfirmation

1) Anlil Brikha
2) Anthony Banks
3) Chad R. Haney
4) Emily A. Waters
5) Fraser Aird
6) Gregory D. Trachiotis
7) Haiwen Luan
8) Igor R. Efimov
9) Irawati Kandela
10) Iwona Stepien
11) Jahyun Koo
12) John A. Rogers
13) John M. Torkelson
14) K. Benjamin Lee
15) Kedar Aras
16) Lori Tran
17) Mengdi Han
18) Mingzheng Wu
19) Min-Ho Seo
20) Nayereh Ghoreishi-Haack
21) Qihui Zhang
22) Quansan Yang
23) Raudel Avila

24) Rose T. Yin
25) Seung Min Lee
26) Sheena W. Chen
27) Shenglian Yao
28) Tong Wang
29) Tong Wei
30) Tzu-Li Liu
31) Wubin Bai
32) Xinge Yu
33) Yameng Xu
34) Yeon Sik Choi
35) Yevgenia Kozorovitskiy
36) Yiyuan Yang
37) Yonggang Huang
38) Yujun Deng
39) Zhaoqian Xie

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Anlil Brikha <brikha.anlil@northwestern.edu> Tue, May 25, 2021 at 2:23 PM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete

— Anlil Brikha

> On May 25, 2021, at 1:58 PM, Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:
>
> Hi Everyone,
>
> Thank you very much for all your contributions to this project. I have updated your affiliation. Please double check the information that let me know whether this is okay for you.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[14,17,21], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[14,17], Nayereh Ghoreishi-Haack[13], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17,21], Xinge Yu[20], Anthony Banks[1,2], Gregory Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,23,24*]
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208,

USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. [†] These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), andjrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

<Author list contribution updated.pdf>

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Anthony Raymond Banks <tbanks@northwestern.edu> Wed, May 26, 2021 at 7:47 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

Quansan,

Congratulations!

I confirm the current author list and the author contributions are correct and complete.

Anthony Banks

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Wednesday, May 26, 2021 12:08 AM
To: Sna Chen <sheena21318@gmail.com>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Anthony Raymond Banks <tbanks@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; Igor Efimov <irefimov@gmail.com>; gtrachiotis@gwu.edu
Subject: Fwd: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Dear all,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by Nature Materials. We are currently doing our final edits to meet the journal guidelines.

I would like you to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Since we are close to the deadline. **It would be perfect if you can send the response to me by the end of this Wednesday (5/26).**

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,18,23], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,18], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,18,23], Xinge Yu[20], Anthony Banks[1,2], Gregory D. Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,15]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,23,24]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [15]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [18]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [19]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Chad R Haney <chad.haney@northwestern.edu> Tue, May 25, 2021 at 2:40 PM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete.

--- Chad Haney

Chad R. Haney, PhD (he/him/his)

Research Associate Professor in

Chemistry Life Processes Institute

Radiology, and Biomedical Engineering

Managing Director

Center for Advanced Molecular Imaging

Northwestern University

2145 Sheridan Road, Room 1535

Evanston, IL 60208-3113

Office: (847) 467-4845

cami

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Tuesday, May 25, 2021 2:34 PM
To: Chad R Haney <chad.haney@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>
Subject: Fwd: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[14,17,23], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[14,17], Nayereh Ghoreishi-Haack[13], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17,23], Xinge Yu[20], Anthony Banks[1,2], Gregory Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,23,24]*

---

[1] Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2] Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3] Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4] Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5] Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6] Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7] Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208,

USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. [†] These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Emily Alexandria Waters <EAlexWaters@northwestern.edu> Tue, May 25, 2021 at 9:47 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

I confirm the author list and contribution are correct and complete.

Emily Alex Waters

PS: Would it be possible to include in your acknowledgement of CAMI our RRID – sort of like an ORCID for core facilities? We just got one assigned, and it will help make our work more searchable.

The ID is RRID:SCR_021192, and it would look something like "MicroCT studies were performed in the Center for Advanced Molecular Imaging (RRID:SCR_021192)."

Please let me know if you have any questions.

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Monday, May 24, 2021 10:20 PM
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <MingzhengWu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <TongWang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; xingeyu@cityu.edu.hk; Anthony Raymond Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu; John M Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Yevgenia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing

100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

fkaird <fkaird@comcast.net> Tue, May 25, 2021 at 4:26 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Author affiliation: 14 Chemistry of Life Processes Institute

I confirm the current author list and the author contribution are correct and complete.
Fraser Aird

Sent from my Verizon, Samsung Galaxy smartphone

-------- Original message --------
From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Date: 5/25/21 2:56 PM (GMT-06:00)
To: fkaird@comcast.net
Subject: Fwd: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory

Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Author confirmation for bioadhesive paper

2 messages

Rose Yin <roseyin@email.gwu.edu> Thu, May 27, 2021 at 10:34 AM
To: "Trachiotis, Gregory D" <Gregory.Trachiotis@va.gov>
Cc: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Dr. Trachiotis,

I know that you have already confirmed the author list, but due to requirements by the Nature Materials editors, we need you to reply to us with the exact following statement if you believe the author list and contributions below are correct and complete:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Thank you for your time!

Best,
Rose

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7,8], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[16,19,24], K. Benjamin Lee[14], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,20], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[16,19], Nayereh Ghoreishi-Haack[15], Lori Tran[15,16], Iwona Stepien[15,16], Fraser Aird[16], Emily A. Waters[16,19,24], Xinge Yu[21], Anthony Banks[1,2], Gregory D. Trachiotis[5,22], John M. Torkelson[4,7], Yonggang Huang[1,3,7,23], Yevgenia Kozorovitskiy[6,16]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,24,25]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Department of Applied Physical Sciences, University of North Carolina at Chapel Hill, NC 27599, USA. [9]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [10]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [11]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [12]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [13]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [14]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [15]Developmental Therapeutics Core, Northwestern University, Evanston, IL 60208,

USA. [16]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [17]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [18]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [19]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [20]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [21]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [22]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [23]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [25]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. [†] These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.R.E., and J.A.R. wrote the manuscript with input from all authors.

--

Rose T. Yin
Ph.D. Candidate in Biomedical Engineering | Efimov Lab | ORCID
The George Washington University
800 22nd St. NW, Suite 5000, Washington DC 20052
she/her/hers

Trachiotis, Gregory D <Gregory.Trachiotis@va.gov> Thu, May 27, 2021 at 11:02 AM
To: Rose Yin <roseyin@email.gwu.edu>
Cc: Quansan Yang <quansanyang2021@u.northwestern.edu>

I confirm the author list and the author contribution are complete and correct.

Gregory Trachiotis, MD

Gregory Trachiotis, MD

Professor of Surgery and Biomedical Engineering

Chief, Cardiothoracic Surgery

Veterans Affairs Medical Center/VISN-5

The George Washington University

Director, Heart Center

Washington DC VAMC

From: Rose Yin <roseyin@email.gwu.edu>
Sent: Thursday, May 27, 2021 11:34 AM
To: Trachiotis, Gregory D <Gregory.Trachiotis@va.gov>
Cc: Quansan Yang <quansanyang2021@u.northwestern.edu>
Subject: [EXTERNAL] Author confirmation for bioadhesive paper

Hi Dr. Trachiotis,

I know that you have already confirmed the author list, but due to requirements by the Nature Materials editors, we need you to reply to us with the exact following statement if you believe the author list and contributions below are correct and complete:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Thank you for your time!

Best,

Rose

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7,8], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7],

Chad R. Haney[16,19,24], K. Benjamin Lee[14], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,20], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[16,19], Nayereh Ghoreishi-Haack[15], Lori Tran[15,16], Iwona Stepien[15,16], Fraser Aird[16], Emily A. Waters[16,19,24], Xinge Yu[21], Anthony Banks[1,2], Gregory D. Trachiotis[5,22], John M. Torkelson[4,7], Yonggang Huang[1,3,7,23], Yevgenia Kozorovitskiy[6,16]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,24,25]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Department of Applied Physical Sciences, University of North Carolina at Chapel Hill, NC 27599, USA. [9]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [10]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [11]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [12]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [13]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [14]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [15]Developmental Therapeutics Core, Northwestern University, Evanston, IL 60208, USA. [16]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [17]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [18]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [19]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [20]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [21]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [22]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [23]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [25]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.R.E., and J.A.R. wrote the manuscript with input from all authors.

--

Rose T. Yin

Ph.D. Candidate in Biomedical Engineering | Efimov Lab | ORCID

The George Washington University

800 22nd St. NW, Suite 5000, Washington DC 20052

she/her/hers

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Haiwen Luan <haiwenluan@u.northwestern.edu> Tue, May 25, 2021 at 10:46 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete.

Haiwen

On Mon, May 24, 2021 at 11:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> ---
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA.

[5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Igor Efimov <irefimov@gmail.com> Wed, May 26, 2021 at 10:04 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Quansan,

I confirm the current author list and the author contribution are correct and complete

Igor R. Efimov, Ph.D.
Editor-in-Chief
Cardiovascular Engineering & Technology

Alisann & Terry Collins Professor
Department of Biomedical Engineering
George Washington University
Washington DC

> On May 26, 2021, at 11:02, Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:
>
> Dear Igor,
>
> I apologize for that. I have changed it accordingly and please let me know if there are any further questions.
>
> Many thanks!
>
> Yours sincerely,
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,18,23], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,18], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,18,23], Xinge Yu[20], Anthony Banks[1,2], Gregory D. Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,15*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,23,24*]
>
> ---
>
> [1] Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2] Querrey Simpson Institute for

> Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14]Developmental Therapeutics Core, Northwestern University, Evanston, IL 60208, USA. [15]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [18]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [19]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).
>
> ## Author contributions
>
> Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.R.E., and J.A.R. wrote the manuscript with input from all authors.
>
> --
>
> On Wed, May 26, 2021 at 4:55 AM Igor Efimov <irefimov@gmail.com> wrote:
>
>> Quansan there is a typo in my middle initial in the last line of Contribution: I.G.E. Please Correct to: I.R.E.
>>
>> Igor Efimov, Ph.D.
>> Alisann & Terry Collins Professor
>> Department of Biomedical Engineering
>> George Washington University
>> Washington DC
>>
>>> On May 26, 2021, at 01:08, Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

Dear all,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by Nature Materials. We are currently doing our final edits to meet the journal guidelines.

I would like you to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"
--- xxx (your name)

Since we are close to the deadline. **It would be perfect if you can send the response to me by the end of this Wednesday (5/26).**

Many thanks. I really appreciate it.

Best regards,
Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,18,23], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,18], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,18,23], Xinge Yu[20], Anthony Banks[1,2], Gregory D. Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,15]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,23,24]*

---

[1] Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2] Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3] Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4] Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5] Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6] Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7] Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8] Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9] School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10] State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11] Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12] Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13] Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14] Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [15] Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16] School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17] State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [18] Center for Advanced Molecular Imaging, Northwestern

University, Evanston, IL 60201, USA. [19]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

<Author list contribution updated.pdf>

<Author list contribution updated.pdf>

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Irawati Kandela <i-kandela@northwestern.edu> Mon, May 24, 2021 at 10:23 PM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

Hi Quansan,

I confirm the current author list and the author contribution are correct and complete

Thanks,
Angki

> On May 24, 2021, at 10:20 PM, Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:
>
> "I confirm the current author list and the author contribution are correct and complete"

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Iwona Stepien <iwona.stepien@northwestern.edu>
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>
Cc: Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>

Fri, May 28, 2021 at 9:57 AM

Hello,

I conform the current author list and the author contribution are correct and complete..

Iwona Stepien

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Friday, May 28, 2021 9:35 AM
To: Iwona Stepien <iwona.stepien@northwestern.edu>
Cc: Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>
Subject: Re: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Dear Iwona,

Could you please use standard sentences to reply to me, as requested by Nature Materials editor.

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Best,

Quansan

On Fri, May 28, 2021 at 9:32 AM Iwona Stepien <iwona.stepien@northwestern.edu> wrote:

> Hello,
>
> I confirm that information are correct.
>
> Iwona Stepien
>
> ---
>
> **From:** Quansan Yang <quansanyang2021@u.northwestern.edu>
> **Sent:** Friday, May 28, 2021 9:29 AM
> **To:** Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>
> **Subject:** Fwd: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"
>
> Hi Nayereh and Iwona,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> ---
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16],

Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7,18], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,19,20], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,21], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,19], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,19,20], Xinge Yu[22], Anthony Banks[1,2], Gregory D. Trachiotis[5,23], John M. Torkelson[4,7], Yonggang Huang[1,3,7,24], Yevgenia Kozorovitskiy[6,15]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,20,25]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14]Developmental Therapeutics Core, Northwestern University, Evanston, IL 60208, USA. [15]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China.[18]Department of Applied Physical Sciences, University of North Carolina at Chapel Hill, NC 27599, USA. [19]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60208, USA. [20]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [21]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, Pusan 43241, Republic of Korea. [22]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [23]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [24]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [25]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo*

> studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.R.E., and J.A.R. wrote the manuscript with input from all authors.
>
> --
> ---

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Jahyun Koo <nano.jhkoo@gmail.com> Mon, May 24, 2021 at 11:57 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan,

"I confirm the current author list and the author contribution are correct and complete" - Jahyun Koo

It was my pleasure to work with you,
Thanks all,
Jahyun

2021년 5월 25일 (화) 오후 12:20, Quansan Yang <quansanyang2021@u.northwestern.edu>님이 작성:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. [†] These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

John A Rogers <jrogers@northwestern.edu> Mon, May 24, 2021 at 10:37 PM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

"I confirm the current author list and the author contribution are correct and complete"

John A. Rogers

From: Quansan Yang [mailto:quansanyang2021@u.northwestern.edu]
Sent: Monday, May 24, 2021 10:20 PM
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <MingzhengWu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <TongWang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; xingeyu@cityu.edu.hk; Anthony Raymond Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu; John M Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Yevgenia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Re: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

John Torkelson <j-torkelson@northwestern.edu>   Tue, May 25, 2021 at 3:57 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

Hello Quansan,

Thank you for your email. It is great to know that the Nature Materials manuscript has been accepted in principle and that soon you will have proofs and then the manuscript will be published. It is truly exciting work, and I am so glad that Tong was able to contribute to it in a meaningful way. As requested, I am providing the statement you wanted.

I confirm the current author list and the author contribution are correct and complete.

John Torkelson

On Mon, May 24, 2021 at 10:21 PM Quansan Yang <QuansanYang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
> ---
>
> Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

--
****

John M. Torkelson
Walter P. Murphy Professor
Dept. of Chemical and Biological Engineering
Dept. of Materials Science and Engineering
Northwestern University
Evanston, IL 60208-3120 USA

Email: j-torkelson@northwestern.edu

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

K. Benjamin Lee <kbenjaminlee@gmail.com> Wed, May 26, 2021 at 4:52 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete.

K. Benjamin Lee

K. Benjamin Lee, MD, PGY5

George Washington University

713-992-4839

On Wed, May 26, 2021, 13:17 Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Dear all,
>
> Please check the updated affiliation and let me know if it is correct for you today.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
> --- xxx (your name)
>
> Best,
> Quansan
>
> ---
>
> Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7,8], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[16,19,24], K. Benjamin Lee[14], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,20], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[16,19], Nayereh Ghoreishi-Haack[15], Lori Tran[15,16], Iwona Stepien[15,16], Fraser Aird[16], Emily A. Waters[16,19,24], Xinge Yu[21], Anthony Banks[1,2], Gregory D. Trachiotis[5,22], John M. Torkelson[4,7], Yonggang Huang[1,3,7,23], Yevgenia Kozorovitskiy[6,16]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,24,25]*
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University,

Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Department of Applied Physical Sciences, University of North Carolina at Chapel Hill, NC 27599, USA. [9]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [10]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [11]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [12]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [13]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [14]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [15]Developmental Therapeutics Core, Northwestern University, Evanston, IL 60208, USA. [16]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [17]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [18]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [19]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [20]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [21]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [22]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [23]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [25]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.R.E., and J.A.R. wrote the manuscript with input from all authors.

On Wed, May 26, 2021 at 3:13 PM Trachiotis, Gregory D <Gregory.Trachiotis@va.gov> wrote:

> Thank you. Rose please add BME at GWU also to my affiliation. I recently was awarded secondary Professor in BME. Thank you Dr. T
>
> Gregory Trachiotis, MD
> Professor of Surgery and Biomedical Engineering
> Chief, Cardiothoracic Surgery
> The George Washington University
> Veterans Affairs Medical Center/ VISN-5
> Director, Heart Center (VAMC)
> Chief, Thoracic Surgery (Sibley Memorial)

From: Rose Yin <roseyin@email.gwu.edu>
Sent: Wednesday, May 26, 2021 4:07:49 PM
To: Sheena Chen <sheenachen@email.gwu.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Trachiotis, Gregory D <Gregory.Trachiotis@va.gov>
Cc: Quansan Yang <quansanyang2021@u.northwestern.edu>
Subject: [EXTERNAL] Re: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Dr. Trachiotis, Sheen, and Benny,

As you may know, our bioadhesive paper has been accepted for publication in Nature Materials. Thanks to Quansan's great leadership, we have been able to achieve incredible results with this project and publish in a journal with an impact factor of 38.663.

Could you please read Quansan's email and let us know whether or not you approve of the author list and contributions? Please also check your affiliations and name spellings.

I suggest the following changes:

For Dr. Trachiotis, please add a middle initial: Gregory D. Trachiotis
For Benny and Sheena, their affiliations are only: *Department of Surgery, The George Washington University, Washington, DC 20052, USA.* Please remove their affiliation to GW BME.

Best,
Rose

On Mon, May 24, 2021 at 11:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

--

Rose T. Yin
Ph.D. Candidate in Biomedical Engineering | Efimov Lab | ORCID
The George Washington University
800 22nd St. NW, Suite 5000, Washington DC 20052
she/her/hers

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Aras, Kedar <kedar_aras@email.gwu.edu> Wed, May 26, 2021 at 12:17 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan

Congratulations!!

"I confirm the current author list and the author contribution are correct and complete"
--- Kedar Aras

Please also include the following grant information in the acknowledgment section - 5K99HL148523-02

Kedar Aras
NIH K99/R00 Postdoctoral Fellow
George Washington University
Science and Engineering Hall
800 22nd St NW
Washington, DC 20052

"If you believe you can or cannot, you are right." - Henry Ford

On Wed, May 26, 2021 at 1:08 AM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Dear all,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by Nature Materials. We are currently doing our final edits to meet the journal guidelines.
>
> I would like you to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> **"I confirm the current author list and the author contribution are correct and complete"**
> **--- xxx (your name)**
>
> Since we are close to the deadline. **It would be perfect if you can send the response to me by the end of this Wednesday (5/26).**
>
> Many thanks. I really appreciate it.
>
> Best regards,
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun

Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,18,23], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,18], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,18,23], Xinge Yu[20], Anthony Banks[1,2], Gregory D. Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,15]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,23,24]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [15]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [18]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [19]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K.,

> I.G.E., and J.A.R. wrote the manuscript with input from all authors.
>
> --

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Lori Tran <phuong.tran@northwestern.edu> Wed, May 26, 2021 at 9:21 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

Hi Quansan,

I confirm the current author list and author contribution are correct and complete.

Lori Tran

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Wednesday, May 26, 2021 12:08 AM
To: Sna Chen <sheena21318@gmail.com>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Anthony Raymond Banks <tbanks@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; Igor Efimov <irefimov@gmail.com>; gtrachiotis@gwu.edu
Subject: Fwd: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Dear all,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by Nature Materials. We are currently doing our final edits to meet the journal guidelines.

I would like you to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Since we are close to the deadline. **It would be perfect if you can send the response to me by the end of this Wednesday (5/26).**

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,18,23], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,19], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,18], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,18,23], Xinge Yu[20], Anthony Banks[1,2], Gregory D. Trachiotis[21], John M. Torkelson[4,7], Yonggang Huang[1,3,7,22], Yevgenia Kozorovitskiy[6,15]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,23,24]*

---

[1] Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2] Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3] Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4] Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5] Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6] Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7] Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8] Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9] School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10] State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11] Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12] Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13] Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14] Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [15] Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16] School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17] State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [18] Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [19] School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea. [20] Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [21] DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [22] Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [23] Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [24] Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and

T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Mengdi Han <hmd@pku.edu.cn> Mon, May 24, 2021 at 10:22 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

"I confirm the current author list and the author contribution are correct and complete"

--- Mengdi Han

------------------ Original ------------------

From: "Quansan Yang" <quansanyang2021@u.northwestern.edu>;
Date: Tue, May 25, 2021 11:20 AM
To: "Tong Wei"<tongwei2014@u.northwestern.edu>;"Yin, Rose"<roseyin@email.gwu.edu>;"Mingzheng Wu"<mingzhengwu2021@u.northwestern.edu>;"Xu, Yameng"<x.yameng@wustl.edu>;"Jahyun Koo"<nano.jhkoo@gmail.com>;"Yeonsik Choi"<yeonsik.choi@northwestern.edu>;"Zhaoqian Xie"<zxie@dlut.edu.cn>;"Sna Chen"<sheena21318@gmail.com>;"Irawati Kandela"<i-kandela@northwestern.edu>;"shenglian_yao"<shenglian_yao@ustb.edu.cn>;"Raudel Oswaldo Avila"<RaudelAvila2023@u.northwestern.edu>;"Tzu-li Liu"<tzu-liliu2020@u.northwestern.edu>;"Wubin Bai"<wbai@northwestern.edu>;"Yiyuan Yang "<yangharlon@gmail.com>;"Mengdi Han"<hanmd1990@gmail.com>;"yjdeng"<yjdeng@sjtu.edu.cn>;"Qihui Zhang"<qihuizhang2019@u.northwestern.edu>;"Chad R Haney"<chad.haney@northwestern.edu>;"K. Benjamin Lee"<kbenjaminlee@gmail.com>;"Kedar Aras"<kedar_aras@gwu.edu>;"Tong Wang"<tongwang2025@u.northwestern.edu>;"Min-Ho Seo"<mhseo@pusan.ac.kr>;"haiwenluan"<haiwenluan@u.northwestern.edu>;"Seung Min Lee"<seung.lee2@northwestern.edu>;"Anlil Brikha"<brikha.anlil@northwestern.edu>;"Nayereh Ghoreishi-Haack"<Nayereh.G.Haack@northwestern.edu>;"Lori Tran"<phuong.tran@northwestern.edu>;"Iwona Stepien"<iwona.stepien@northwestern.edu>;"Fraser Aird"<fraser.aird@northwestern.edu>;"Emily Alexandria Waters"<EAlexWaters@northwestern.edu>;"xingeyu"<xingeyu@cityu.edu.hk>;"Anthony R Banks"<tbanks@northwestern.edu>;"gtrachiotis"<gtrachiotis@gwu.edu>;"John Torkelson"<j-torkelson@northwestern.edu>;"Yonggang Huang"<y-huang@northwestern.edu>;"Genia Kozorovitskiy"<yevgenia.kozorovitskiy@northwestern.edu>;"Igor Efimov"<efimov@email.gwu.edu>;"John A Rogers"<jrogers@northwestern.edu>;
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-

Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Mingzheng Wu <mingzhengwu2021@u.northwestern.edu> Tue, May 25, 2021 at 12:35 PM

To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan,

I confirm the current author list and the author contribution are correct and complete.

Best,
Mingzheng

On Mon, May 24, 2021 at 10:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*
>
> ---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

mhseo@pusan.ac.kr <mhseo@pusan.ac.kr> Mon, May 24, 2021 at 11:30 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Dear Quansan,

Quansan, Thanks for your good news.

As I asked you before, could you please add my current affliation?

(That is very important for me recently, haha)

Min-Ho Seo, School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, 49, Busandaehak-ro, Yangsan-si, Gyeongsangnam-do, Republic of Korea.

Except that, I "I confirm the current author list and the author contribution are correct and complete" – Min-Ho Seo

Congrats on your Nat. Mat. Once more.

King regards,

Min-Ho

Min-Ho Seo, Ph.D

Assistant Professor

Department of Biomedical Convergence Engineering, School of Information and Biomedical Engineering (https://bce.pusan.ac.kr)

Pusan National University, Yangsan, Korea

Tel: +82-51-510-8558

E-mail: mhseo@pusan.ac.kr

Lab: https://sites.google.com/view/mhseogroup

보낸 사람: Quansan Yang
보낸 날짜: 2021년 5월 25일 화요일 오후 12:20
받는 사람: Tong Wei; Yin, Rose; Mingzheng Wu; Xu, Yameng; Jahyun Koo; Yeonsik Choi; Zhaoqian Xie; Sna Chen; Irawati Kandela; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila; Tzu-li Liu; Wubin Bai; Yiyuan Yang <yangharlon@gmail.com>; Mengdi Han; yjdeng@sjtu.edu.cn; Qihui Zhang; Chad R Haney; K. Benjamin Lee; Kedar Aras; Tong Wang; Min-Ho Seo; haiwenluan@u.northwestern.edu; Seung Min Lee; Anlil Brikha; Nayereh Ghoreishi-Haack; Lori Tran; Iwona Stepien; Fraser Aird; Emily Alexandria Waters; xingeyu@cityu.edu.hk; Anthony R Banks; gtrachiotis@gwu.edu; John Torkelson; Yonggang Huang; Genia Kozorovitskiy; Igor Efimov; John A Rogers
제목: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu> Fri, May 28, 2021 at 9:31 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>, Iwona Stepien <iwona.stepien@northwestern.edu>

"I confirm the current author list and the author contribution are correct and complete"

Nayereh Ghoreishi-Haack

Thank you,

N.

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Friday, May 28, 2021 9:29 AM
To: Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>
Subject: Fwd: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Nayereh and Iwona,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[13], Irawati Kandela[14,15], Shenglian Yao[16], Yujun Deng[3,17], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7,18], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[15,19,20], K. Benjamin Lee[13], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7,21], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[15,19], Nayereh Ghoreishi-Haack[14], Lori Tran[14,15], Iwona Stepien[14,15], Fraser Aird[15], Emily A. Waters[15,19,20], Xinge Yu[22], Anthony Banks[1,2], Gregory D. Trachiotis[5,23], John M. Torkelson[4,7], Yonggang Huang[1,3,7,24], Yevgenia Kozorovitskiy[6,15]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,20,25]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [14]Developmental Therapeutics Core, Northwestern University, Evanston, IL 60208, USA. [15]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [16]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [17]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China.[18]Department of Applied Physical Sciences, University of North Carolina at Chapel Hill, NC 27599, USA. [19]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60208, USA. [20]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [21]School of Biomedical Convergence Engineering, College of Information & Biomedical Engineering, Pusan National University, Pusan 43241, Republic of Korea. [22]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [23]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [24]Departments of Civil and Environmental Engineering, Northwestern University, Evanston, IL 60208, USA. [25]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.R.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Qihui Zhang <qihuizhang2019@u.northwestern.edu> Mon, May 24, 2021 at 10:49 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete

-Qihui Zhang

Congratulations Quansan! Where is your next stop for post-doc? Direct-to-AP also sounds good haha :)

On Tue, May 25, 2021 at 11:20 AM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for

Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Quansan Yang <quansanyang2021@u.northwestern.edu>

Mon, May 24, 2021 at 10:20 PM

To: Tong Wei <tongwei2014@u.northwestern.edu>, "Yin, Rose" <roseyin@email.gwu.edu>, Mingzheng Wu <mingzhengwu2021@u.northwestern.edu>, "Xu, Yameng" <x.yameng@wustl.edu>, Jahyun Koo <nano.jhkoo@gmail.com>, Yeonsik Choi <yeonsik.choi@northwestern.edu>, Zhaoqian Xie <zxie@dlut.edu.cn>, Sna Chen <sheena21318@gmail.com>, Irawati Kandela <i-kandela@northwestern.edu>, shenglian_yao@ustb.edu.cn, Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>, Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>, Wubin Bai <wbai@northwestern.edu>, "Yiyuan Yang <yangharlon@gmail.com>" <yangharlon@gmail.com>, Mengdi Han <hanmd1990@gmail.com>, yjdeng@sjtu.edu.cn, Qihui Zhang <qihuizhang2019@u.northwestern.edu>, Chad R Haney <chad.haney@northwestern.edu>, "K. Benjamin Lee" <kbenjaminlee@gmail.com>, Kedar Aras <kedar_aras@gwu.edu>, Tong Wang <tongwang2025@u.northwestern.edu>, Min-Ho Seo <mhseo@pusan.ac.kr>, haiwenluan@u.northwestern.edu, Seung Min Lee <seung.lee2@northwestern.edu>, Anlil Brikha <brikha.anlil@northwestern.edu>, Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>, Lori Tran <phuong.tran@northwestern.edu>, Iwona Stepien <iwona.stepien@northwestern.edu>, Fraser Aird <fraser.aird@northwestern.edu>, Emily Alexandria Waters <EAlexWaters@northwestern.edu>, xingeyu@cityu.edu.hk, Anthony R Banks <tbanks@northwestern.edu>, gtrachiotis@gwu.edu, John Torkelson <j-torkelson@northwestern.edu>, Yonggang Huang <y-huang@northwestern.edu>, Genia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>, Igor Efimov <efimov@email.gwu.edu>, John A Rogers <jrogers@northwestern.edu>

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

\---

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory

Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Author list and contribution.pdf
95K

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Raudel Avila <raudelavila2023@u.northwestern.edu> Mon, May 24, 2021 at 10:22 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan,

Congrats on the paper acceptance!

I confirm the current author list and the author contribution are correct and complete.

- Raudel Avila

On Mon, May 24, 2021 at 10:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> ---
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]
>
> ---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

--
Raudel O. Avila

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Rose Yin <roseyin@email.gwu.edu> Tue, May 25, 2021 at 8:07 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>
Cc: "Xu, Yameng" <x.yameng@wustl.edu>

Hi Quansan,

I would like to request the following changes:

For Gregory Trachiotis, please add his middle initial: Gregory D. Trachiotis

For Benny and Sheena, their affiliations are *only*: Department of Surgery, The George Washington University, Washington, DC 20052, USA

Please remove their affiliation to BME.

Otherwise, everything is correct, and I confirm that the author list and the author contribution are correct and complete.

Best,
Rose

On Mon, May 24, 2021 at 11:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori

Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

--
Rose T. Yin
Ph.D. Candidate in Biomedical Engineering | Efimov Lab | ORCID

The George Washington University
800 22nd St. NW, Suite 5000, Washington DC 20052
she/her/hers

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

이승민 <klsm1213@snu.ac.kr> Mon, May 24, 2021 at 10:50 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan!

Huge congratulations to your new paper!

I confirm the current author list and the author contribution are correct and complete.

Seung Min Lee

2021년 5월 25일 (화) 오후 12:39, Quansan Yang <quansanyang2021@u.northwestern.edu>님이 작성:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Chen, Sheena <sheenachen@email.gwu.edu> Wed, May 26, 2021 at 7:48 PM
To: Rose Yin <roseyin@email.gwu.edu>
Cc: "K. Benjamin Lee" <kbenjaminlee@gmail.com>, Quansan Yang <quansanyang2021@u.northwestern.edu>, "Trachiotis, Gregory D" <Gregory.Trachiotis@va.gov>

Thanks Rose and Quansan,

As Rose mentioned, my affiliation is with the Department of Surgery, George Washington University. My name is correct.

I confirm the current author list and the author contribution are correct and complete.

Thanks!

Sheena

On Wed, May 26, 2021 at 16:08 Rose Yin <roseyin@email.gwu.edu> wrote:

> Hi Dr. Trachiotis, Sheen, and Benny,
>
> As you may know, our bioadhesive paper has been accepted for publication in Nature Materials. Thanks to Quansan's great leadership, we have been able to achieve incredible results with this project and publish in a journal with an impact factor of 38.663.
>
> Could you please read Quansan's email and let us know whether or not you approve of the author list and contributions? Please also check your affiliations and name spellings.
>
> I suggest the following changes:
>
> For Dr. Trachiotis, please add a middle initial: Gregory D. Trachiotis
> For Benny and Sheena, their affiliations are only: *Department of Surgery, The George Washington University, Washington, DC 20052, USA.* Please remove their affiliation to GW BME.
>
> Best,
> Rose
>
> On Mon, May 24, 2021 at 11:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:
>
>> Hi Everyone,
>>
>> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>>
>> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>>
>> "I confirm the current author list and the author contribution are correct and complete"
>>
>> --- xxx (your name)
>>
>> Many thanks. I really appreciate it.
>>
>> Best regards,
>>
>> Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A.,

> and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.
>
> --
> ---

--
Rose T. Yin
Ph.D. Candidate in Biomedical Engineering | Efimov Lab | ORCID
The George Washington University
800 22nd St. NW, Suite 5000, Washington DC 20052
she/her/hers

--
Sheena Chen, MD
General Surgery Resident
George Washington University

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

姚生莲 <shenglian_yao@ustb.edu.cn> Tue, May 25, 2021 at 1:26 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan,
Congratulations!

I confirm the current author list and the author contribution are correct and complete.

Shenglian Yao

Best

> -----原始邮件-----
> **发件人:**"Quansan Yang" <quansanyang2021@u.northwestern.edu>
> **发送时间:**2021-05-25 11:20:22 (星期二)
> **收件人:** "Tong Wei" <tongwei2014@u.northwestern.edu>, "Yin, Rose" <roseyin@email.gwu.edu>, "Mingzheng Wu" <mingzhengwu2021@u.northwestern.edu>, "Xu, Yameng" <x.yameng@wustl.edu>, "Jahyun Koo" <nano.jhkoo@gmail.com>, "Yeonsik Choi" <yeonsik.choi@northwestern.edu>, "Zhaoqian Xie" <zxie@dlut.edu.cn>, "Sna Chen" <sheena21318@gmail.com>, "Irawati Kandela" <i-kandela@northwestern.edu>, shenglian_yao@ustb.edu.cn, "Raudel Oswaldo Avila" <RaudelAvila2023@u.northwestern.edu>, "Tzu-li Liu" <tzu-liliu2020@u.northwestern.edu>, "Wubin Bai" <wbai@northwestern.edu>, "Yiyuan Yang <yangharlon@gmail.com>" <yangharlon@gmail.com>, "Mengdi Han" <hanmd1990@gmail.com>, yjdeng@sjtu.edu.cn, "Qihui Zhang" <qihuizhang2019@u.northwestern.edu>, "Chad R Haney" <chad.haney@northwestern.edu>, "K. Benjamin Lee" <kbenjaminlee@gmail.com>, "Kedar Aras" <kedar_aras@gwu.edu>, "Tong Wang" <tongwang2025@u.northwestern.edu>, "Min-Ho Seo" <mhseo@pusan.ac.kr>, haiwenluan@u.northwestern.edu, "Seung Min Lee" <seung.lee2@northwestern.edu>, "Anlil Brikha" <brikha.anlil@northwestern.edu>, "Nayereh Ghoreishi-Haack" <Nayereh.G.Haack@northwestern.edu>, "Lori Tran" <phuong.tran@northwestern.edu>, "Iwona Stepien" <iwona.stepien@northwestern.edu>, "Fraser Aird" <fraser.aird@northwestern.edu>, "Emily Alexandria Waters" <EAlexWaters@northwestern.edu>, xingeyu@cityu.edu.hk, "Anthony R Banks" <tbanks@northwestern.edu>, gtrachiotis@gwu.edu, "John Torkelson" <j-torkelson@northwestern.edu>, "Yonggang Huang" <y-huang@northwestern.edu>, "Genia Kozorovitskiy" <yevgenia.kozorovitskiy@northwestern.edu>, "Igor Efimov" <efimov@email.gwu.edu>, "John A Rogers" <jrogers@northwestern.edu>
> **抄送:**
> **主题:** Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"
>
> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. [†] These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies.

> Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.
>
> --
> --

--

School of Materials Science and Engineering, University of Science and Technology Beijing
No. 30, Xueyuan Road, Haidian District, Beijing, China, 100083

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Tong Wang <tongwang2025@u.northwestern.edu> Tue, May 25, 2021 at 9:32 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

"I confirm the current author list and the author contribution are correct and complete"

--- Tong Wang

On Mon, May 24, 2021 at 10:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA.

[5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Tong Wei <tongwei2014@u.northwestern.edu> Tue, May 25, 2021 at 8:31 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan,

Thank you for the great work!

I confirm the current author list and the author contribution are correct and complete.

Regards,
Tong Wei

On Mon, May 24, 2021 at 22:20 Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

--
Tong Wei
PhD Candidate, Torkelson Research Group
Department of Chemical and Biological Engineering, McCormick School of Engineering
Northwestern University

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Mon, May 24, 2021 at 11:14 PM

I confirm the current author list and the author contribution are correct and complete

--- Tzu-Li Liu

On Mon, May 24, 2021, 23:20 Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of

Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Wubin Bai <wbai@northwestern.edu> Tue, May 25, 2021 at 7:22 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

Thank you very much for the opportunity, Quansan.

I confirm the current author list and the author contribution are correct and complete.

--- Wubin Bai

Sincerely,

Wubin

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Monday, May 24, 2021 11:20 PM
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <MingzhengWu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <TongWang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; xingeyu@cityu.edu.hk; Anthony Raymond Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu; John M Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Yevgenia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing

100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Dr. YU Xinge <xingeyu@cityu.edu.hk> Tue, May 25, 2021 at 12:07 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Hi Quansan,

Big congratulations to you!

"I confirm the current author list and the author contribution are correct and complete"

Xinge Yu

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Tuesday, May 25, 2021 11:20 AM
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <mingzhengwu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <tongwang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; Dr. YU Xinge <xingeyu@cityu.edu.hk>; Anthony R Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu; John Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Genia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA.

[15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Disclaimer: This email (including any attachments) is for the use of the intended recipient only and may contain confidential information and/or copyright material. If you are not the intended recipient, please notify the sender immediately and delete this email and all copies from your system. Any unauthorized use, disclosure, reproduction, copying, distribution, or other form of unauthorized dissemination of the contents is expressly prohibited.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Xu, Yameng <x.yameng@wustl.edu> Tue, May 25, 2021 at 11:41 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Dear Quansan,

I confirm the current author list and the author contribution are correct and complete.

Yameng Xu

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Monday, May 24, 2021 22:20
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <mingzhengwu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn <shenglian_yao@ustb.edu.cn>; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn <yjdeng@sjtu.edu.cn>; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <tongwang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu <haiwenluan@u.northwestern.edu>; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; xingeyu@cityu.edu.hk <xingeyu@cityu.edu.hk>; Anthony R Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu <gtrachiotis@gwu.edu>; John Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Genia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H.,

K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Yeonsik Choi <yeonsik.choi@northwestern.edu> Tue, May 25, 2021 at 6:05 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete

Many thanks,

Yeon Sik Choi

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Tuesday, May 25, 2021 12:20 PM
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <MingzhengWu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <TongWang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; xingeyu@cityu.edu.hk; Anthony Raymond Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu; John M Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Yevgenia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu

(J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Re: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Genia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>

Tue, May 25, 2021 at 7:50 AM

To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete.

Yevgenia Kozorovitskiy

On Mon, May 24, 2021 at 10:21 PM Quansan Yang <QuansanYang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]
>
> ---
>
> [1] Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2] Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3] Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4] Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA.

> [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).
>
> ## Author contributions
>
> Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.
>
> --
> --

--
Yevgenia Kozorovitskiy

Soretta and Henry Shapiro Research Professor of Molecular Biology
Associate Professor
Department of Neurobiology
Northwestern University

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Yiyuan Yang <yangharlon@gmail.com> Tue, May 25, 2021 at 10:58 AM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

Congratulations Quansan!

"I confirm the current author list and the author contribution are correct and complete"

Yiyuan Yang

On Mon, May 24, 2021 at 10:20 PM Quansan Yang <quansanyang2021@u.northwestern.edu> wrote:

> Hi Everyone,
>
> Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.
>
> I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:
>
> "I confirm the current author list and the author contribution are correct and complete"
>
> --- xxx (your name)
>
> Many thanks. I really appreciate it.
>
> Best regards,
>
> Quansan
>
> --
>
> Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*
>
> ---
>
> [1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University,

Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. [†] These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Yonggang Huang <y-huang@northwestern.edu> Tue, May 25, 2021 at 5:46 AM
To: Quansan Yang <QuansanYang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete

Yonggang

From: Quansan Yang <quansanyang2021@u.northwestern.edu>
Sent: Monday, May 24, 2021 10:20 PM
To: Tong Wei <tongwei2014@u.northwestern.edu>; Yin, Rose <roseyin@email.gwu.edu>; Mingzheng Wu <MingzhengWu2021@u.northwestern.edu>; Xu, Yameng <x.yameng@wustl.edu>; Jahyun Koo <nano.jhkoo@gmail.com>; Yeonsik Choi <yeonsik.choi@northwestern.edu>; Zhaoqian Xie <zxie@dlut.edu.cn>; Sna Chen <sheena21318@gmail.com>; Irawati Kandela <i-kandela@northwestern.edu>; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila <RaudelAvila2023@u.northwestern.edu>; Tzu-li Liu <tzu-liliu2020@u.northwestern.edu>; Wubin Bai <wbai@northwestern.edu>; Yiyuan Yang <yangharlon@gmail.com> <yangharlon@gmail.com>; Mengdi Han <hanmd1990@gmail.com>; yjdeng@sjtu.edu.cn; Qihui Zhang <qihuizhang2019@u.northwestern.edu>; Chad R Haney <chad.haney@northwestern.edu>; K. Benjamin Lee <kbenjaminlee@gmail.com>; Kedar Aras <kedar_aras@gwu.edu>; Tong Wang <TongWang2025@u.northwestern.edu>; Min-Ho Seo <mhseo@pusan.ac.kr>; haiwenluan@u.northwestern.edu; Seung Min Lee <seung.lee2@northwestern.edu>; Anlil Brikha <brikha.anlil@northwestern.edu>; Nayereh Ghoreishi-Haack <Nayereh.G.Haack@northwestern.edu>; Lori Tran <phuong.tran@northwestern.edu>; Iwona Stepien <iwona.stepien@northwestern.edu>; Fraser Aird <fraser.aird@northwestern.edu>; Emily Alexandria Waters <EAlexWaters@northwestern.edu>; xingeyu@cityu.edu.hk; Anthony Raymond Banks <tbanks@northwestern.edu>; gtrachiotis@gwu.edu; John M Torkelson <j-torkelson@northwestern.edu>; Yonggang Huang <y-huang@northwestern.edu>; Yevgenia Kozorovitskiy <yevgenia.kozorovitskiy@northwestern.edu>; Igor Efimov <efimov@email.gwu.edu>; John A Rogers <jrogers@northwestern.edu>
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3]†, Tong Wei[4]†, Rose T. Yin[5]†, Mingzheng Wu[6]†, Yameng Xu[7,8]†, Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern

Quansan Yang <quansanyang2021@u.northwestern.edu>

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

---

yjdeng@sjtu.edu.cn <yjdeng@sjtu.edu.cn> Tue, May 25, 2021 at 8:43 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

"I confirm the current author list and the author contribution are correct and complete"

Yujun Deng

yjdeng@sjtu.edu.cn

From: Quansan Yang
Date: 2021-05-25 11:20
To: Tong Wei; Yin, Rose; Mingzheng Wu; Xu, Yameng; Jahyun Koo; Yeonsik Choi; Zhaoqian Xie; Sna Chen; Irawati Kandela; shenglian_yao; Raudel Oswaldo Avila; Tzu-li Liu; Wubin Bai; Yiyuan Yang <yangharlon@gmail.com>; Mengdi Han; yjdeng; Qihui Zhang; Chad R Haney; K. Benjamin Lee; Kedar Aras; Tong Wang; Min-Ho Seo; haiwenluan; Seung Min Lee; Anlil Brikha; Nayereh Ghoreishi-Haack; Lori Tran; Iwona Stepien; Fraser Aird; Emily Alexandria Waters; xingeyu; Anthony R Banks; gtrachiotis; John Torkelson; Yonggang Huang; Genia Kozorovitskiy; Igor Efimov; John A Rogers
Subject: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory

Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14]*, Igor R. Efimov[5]*, John A. Rogers[1,2,3,7,21,22]*

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.

Northwestern **Quansan Yang <quansanyang2021@u.northwestern.edu>**

Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Zhaoqian Xie <zxie@dlut.edu.cn> Mon, May 24, 2021 at 11:21 PM
To: Quansan Yang <quansanyang2021@u.northwestern.edu>

I confirm the current author list and the author contribution are correct and complete.

Zhaoqian Xie

发件人: Quansan Yang
发送时间: 2021年5月25日星期二 上午11:20
收件人: Tong Wei; Yin, Rose; Mingzheng Wu; Xu, Yameng; Jahyun Koo; Yeonsik Choi; Zhaoqian Xie; Sna Chen; Irawati Kandela; shenglian_yao@ustb.edu.cn; Raudel Oswaldo Avila; Tzu-li Liu; Wubin Bai; Yiyuan Yang <yangharlon@gmail.com>; Mengdi Han; yjdeng@sjtu.edu.cn; Qihui Zhang; Chad R Haney; K. Benjamin Lee; Kedar Aras; Tong Wang; Min-Ho Seo; haiwenluan@u.northwestern.edu; Seung Min Lee; Anlil Brikha; Nayereh Ghoreishi-Haack; Lori Tran; Iwona Stepien; Fraser Aird; Emily Alexandria Waters; xingeyu@cityu.edu.hk; Anthony R Banks; gtrachiotis@gwu.edu; John Torkelson; Yonggang Huang; Genia Kozorovitskiy; Igor Efimov; John A Rogers
主题: Author list and contribution for paper "Photocurable bioresorbable adhesives as functional interfaces between flexible bioelectronic devices and soft biological tissues"

Hi Everyone,

Thank you very much for all your contributions to this project. The paper is now accepted in principle by *Nature Materials*. We are currently doing our final edits to meet the journal guidelines.

I would like all the authors to confirm is the author list and the author contribution attached as follows (also in the attached file) are correct and complete by replying this email with the statement:

"I confirm the current author list and the author contribution are correct and complete"

--- xxx (your name)

Many thanks. I really appreciate it.

Best regards,

Quansan

Quansan Yang[1,2,3†], Tong Wei[4†], Rose T. Yin[5†], Mingzheng Wu[6†], Yameng Xu[7,8†], Jahyun Koo[9], Yeon Sik Choi[1,2,7], Zhaoqian Xie[10,11,12], Sheena W. Chen[5], Irawati Kandela[13,14], Shenglian Yao[15], Yujun Deng[3,16], Raudel Avila[3], Tzu-Li Liu[3], Wubin Bai[1,2,7], Yiyuan Yang[1,2,3], Mengdi Han[1,2], Qihui Zhang[7], Chad R. Haney[13,17], K. Benjamin Lee[5,18], Kedar Aras[5], Tong Wang[4], Min-Ho Seo[1,2,7], Haiwen Luan[1,2,3], Seung Min Lee[7], Anlil Brikha[13,17], Nayereh Ghoreishi-Haack[13,14], Lori Tran[13,14], Iwona Stepien[13,14], Fraser Aird[13,14], Emily A. Waters[14,17], Xinge Yu[19], Anthony Banks[1,2], Gregory Trachiotis[20], John M. Torkelson[4,7], Yonggang Huang[1,2,3,7], Yevgenia Kozorovitskiy[6,14*], Igor R. Efimov[5*], John A. Rogers[1,2,3,7,21,22*]

---

[1]Center for Bio-Integrated Electronics, Northwestern University, Evanston, IL 60208, USA. [2]Querrey Simpson Institute for Biotechnology, Northwestern University, Evanston, IL 60208, USA. [3]Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208, USA. [4]Department of Chemical and Biological Engineering, Northwestern University, Evanston, IL 60208, USA. [5]Department of Biomedical Engineering, The George Washington University, Washington, DC, 20052, USA. [6]Department of Neurobiology, Northwestern University, Evanston, IL 60208, USA. [7]Department of Materials Science and Engineering, Northwestern University, Evanston, IL 60208, USA. [8]Institute of Materials Science and Engineering, Washington University in St. Louis, St. Louis, MO 63130, USA. [9]School of Biomedical Engineering, Korea University, Seoul 02841, Republic of Korea. [10]State Key Laboratory of Structural Analysis for Industrial Equipment, Dalian University of Technology, Dalian 116024, China. [11]Department of Engineering Mechanics, Dalian University of Technology, Dalian 116024, China. [12]Ningbo Institute of Dalian University of Technology, Ningbo, 315016, China. [13]Center for Developmental Therapeutics, Northwestern University, Evanston, IL 60208, USA. [14]Chemistry Life Processes Institute, Northwestern University, Evanston, IL 60208, USA. [15]School of Materials Science and Engineering, University of Science & Technology Beijing, Beijing 100083, China. [16]State Key Laboratory of Mechanical System and Vibration, Shanghai Jiao Tong University, Shanghai 200240, China. [17]Center for Advanced Molecular Imaging, Northwestern University, Evanston, IL 60201, USA. [18]Department of Surgery, The George Washington University, Washington, DC 20052, USA. [19]Department of Biomedical Engineering, City University of Hong Kong, Hong Kong 999077, China. [20]DC Veterans Affairs Medical Center, The George Washington University, Washington, DC 20052, USA. [21]Department of Biomedical Engineering, Northwestern University, Evanston, IL 60208, USA. [22]Department of Neurological Surgery, Feinberg School of Medicine, Northwestern University, Chicago, IL 60611, USA. † These authors contributed equally to this work. * To whom correspondence should be addressed to yevgenia.kozorovitskiy@northwestern.edu (Y.K.), efimov@gwu.edu (I.R.E.), and jrogers@northwestern.edu (J.A.R.).

Author contributions

Q.Y., T.W., Y.K., I.R.E., and J.A.R. conceived the ideas and designed the research. Q.Y., T.W., Y.X., and T.L.L. synthesized and characterized the materials. Q.Y., Y.X., J.K., Y.S.C., W.B., Y.Y., M.H., Q.Z., M.H.S., S.M.L., and A.B. designed and fabricated the devices. R.T.Y., M.W., S.W.C., I.K., S.Y., C.R.H., K.B.L., K.A., A.B., I.S., F.A., E.A.W., and G.T. performed the *in vitro*, *ex vivo*, and *in vivo* studies. Q.Y., R.T.Y, Y.X., M.W., C.R.H., A.B., and E.A.W. performed the data analysis. Z.X., R.A., and Y.D. performed the mechanical and electrical modelling. Q.Y., Y.X., R.T.Y., T.W., M.W, J.M.T., Y.H., Y.K., I.G.E., and J.A.R. wrote the manuscript with input from all authors.
